

Specifications

Designed to support applications such as: SOHO (ADSL Modems), LAN-on-Motherboard (LOM), Hub and Switches. Meets IEEE 802.3 specification.

Materials:

Housing: Thermoplastic UL94V-0

Contact/Shield: Copper Alloy

Shield Plating: Nickel

Contact Plating: Gold 6μ" min. in contact area

Wave solder tip temperature: 265°C Max for 5 Sec Max

Electrical Specifications @25°C

Operating Temperature Range: 0°C to 70°C

Turn Ratio (±2%):

TX = 1CT:1CT, RX = 1CT:1CT

Inductance OCL:

350μH Min @ 100KHz, 0.1V, 8mA

Insertion Loss:

-1.0dB Max @ 1.0-65MHz

Return Loss: (@100Ω ± 15Ω)

-18dB Min @ 1.0-10MHz

-14dB Min @ 10-30MHz

-12dB Min @ 30-60MHz

-10dB Min @ 60-80MHz

Cross Talk:

-35dB Min @ 1.0-30MHz

-35dB Min @ 30-60MHz

-30dB Min @ 60-100MHz

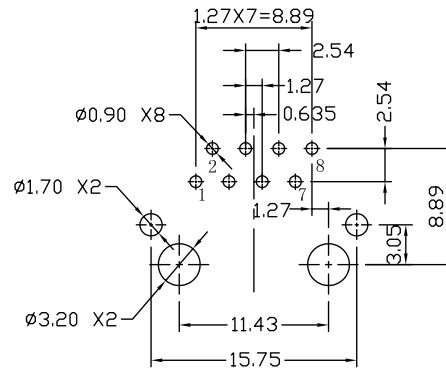
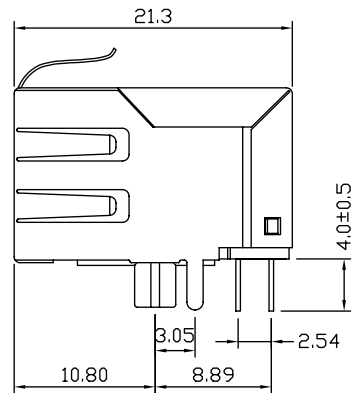
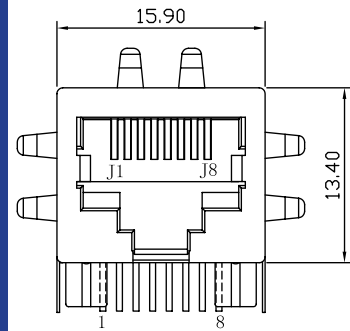
Common Mode Rejection:

-20dB Min @ 1.0-50MHz

-15dB Min @ 50-150MHz

Hipot Test: 1500Vrms Min

General Tolerance	
.X ± 0.30	Angles: ±1°
.XX ± 0.20	
.XXX ± 0.05	
Units : mm	



SUGGESTED PCB LAYOUT(TOP VIEW)

